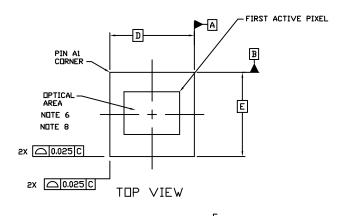
## ODCSP63, 6.198x6.178

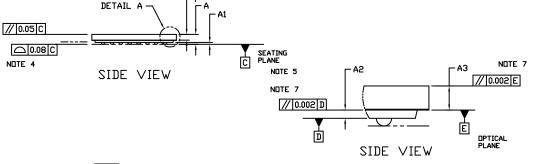
CASE 570BY ISSUE B

**DATE 05 JAN 2018** 

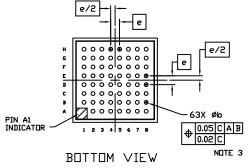


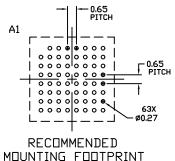
## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSION  $\updeta$  IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE ±0.1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
- 7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
- 8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=-23.56 MICRONS, Y=96.96 MICRONS ±25 MICRONS.



	MILLIMETERS	
DIM	MIN.	MAX.
Α		0.81
A1	0.11	0.17
A2	0.125	0.175
A3	0.421	0.461
b	0.25	0.31
D	6.198 BSC	
Ε	6.178 BSC	
е	0.65 BSC	
F	0.38	0.42





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